


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32H562AGI6	24OQ*484XXX	A	9991	26-07-2023
	Amount	UoM	Unit type	ST ECOPACK Grade
	64.68	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	NAC	Copper Alloy	96.5SN/3.5AG_0.20MM	

Package Designator	Size	Nbr of instances	Shape	
BGA	7x7	169	bulk solder	
Comment	Package : A0YV UFBGA 7X7X0.6 169L P 0.5 MM 8502430			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	240Q*484XXXX				9999999.0	999999.1
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	2.028	mg	supplier	die	Silicon (Si)	7440-21-3		1.657	mg	817061	25618
				supplier	metallization	Aluminium (Al)	7429-90-5		0.044	mg	21696	680
				supplier	metallization	Copper (Cu)	7440-50-8		0.138	mg	68047	2134
				supplier	metallization	Nickel (Ni)	7440-02-0		0.001	mg	493	15
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.022	mg	10848	340
				supplier	metallization	Titanium (Ti)	7440-32-6		0.004	mg	1972	62
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	493	15
				supplier	Passivation	Silicon Oxide	7631-86-9		0.161	mg	79389	2489
				supplier	BT-substrate	Thermosetting resin (Inorganic filler)	Proprietary		1.557	mg	80000	24076
				supplier	BT-substrate	Glass cloth	65997-17-3		6.229	mg	320000	96305
Substrate (A296840)	M-011 Other inorganic materials	19.466	mg	supplier	BT-substrate	Copper foil	7440-50-8		7.008	mg	360000	108343
				supplier	Solder mask	3-methoxy-3-methylbutylacetate	103429-90-9		0.973	mg	50000	15048
				supplier	Solder mask	Morpholinederivative	Proprietary		0.195	mg	10000	3010
				supplier	Solder mask	Barium Sulfate	7727-43-7		2.336	mg	120000	36114
				supplier	Solder mask	Talc containing no as bestifrom fibers	14807-96-6		0.097	mg	5000	1505
				supplier	Solder mask	Dipropylene glycol monomethyl ether	34590-94-8		1.071	mg	55000	16552
				supplier	film	Butadiene, acrylonitrile polymer, carboxy-term	68610-41-3		2.035	mg	686250	31458
				supplier	film	Formaldehyde, polymer with (chloromethyl)ox	37382-79-9		0.871	mg	293750	13466
				supplier	film	[3-(2,3-Epoxypropoxy)propyl]trimethoxysilane	2530-83-8		0.030	mg	10000	458
				supplier	film	Reaction product: bisphenol-A-(epichlorhydrin)	25068-38-6		0.030	mg	10000	458
Bonding wire (Cu)	Precious metals	1.972	mg	supplier	Bonding wire	Gold (Au)	7440-57-5		0.006	mg	3000	91
				supplier	Bonding wire	Copper (Cu)	7440-50-8		1.927	mg	977000	29787
				supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.039	mg	20000	610
				supplier	Molding Compound	Epoxy resin	Proprietary		1.366	mg	40000	21113
Encapsulation (KE-G1250AAS)	M-011 Other inorganic materials	34.140	mg	supplier	Molding Compound	Silica(Fused)	60676-86-0,7631-86-9		30.726	mg	900000	475039
				supplier	Molding Compound	Phenol resin	Proprietary		1.912	mg	56000	29558
				supplier	Molding Compound	Carbon Black	1333-86-4		0.137	mg	4000	2111
				supplier	Solder	Tin (Sn)	7440-31-5		3.966	mg	965000	61319
Solderballs (96.5Sn/3.5Ag)	Solder	4.110	mg	supplier	Solder	Silver (Ag)	7440-22-4		0.144	mg	35000	2224